

L Number	Hits	Search Text	DB	Time stamp
-	163	(IC adj package).ti.	USPAT; US-PGPUB	2003/03/22 17:27
-	216	(IC adj package).ti.	USPAT; US-PGPUB	2003/03/22 11:05
-	16	((IC adj package).ti.) and 324/\$.ccls.	USPAT; US-PGPUB	2003/03/22 11:15
-	2	((((IC adj package).ti.) and 439/\$.ccls.) and bond	USPAT; US-PGPUB	2003/03/22 11:14
-	1	((((IC adj package).ti.) and 324/\$.ccls.) and bond	USPAT; US-PGPUB	2003/03/22 11:14
-	432	324/\$.ccls. and package and adhesive and chip	USPAT; US-PGPUB	2003/03/22 11:15
-	280	324/\$.ccls. and package and adhesive and chip and bond	USPAT; US-PGPUB	2003/03/22 11:15
-	19	324/\$.ccls. and package and adhesive and chip and bond and indium	USPAT; US-PGPUB	2003/03/22 12:42
-	36	((IC adj package).ti.) and 439/\$.ccls.	USPAT; US-PGPUB	2003/03/22 11:49
-	5166	(package near comprising).clm.	USPAT; US-PGPUB	2003/03/22 11:50
-	0	((package near comprising).clm.) and conductive near2 adhesive	USPAT; US-PGPUB	2003/03/22 11:53
-	1	((package near comprising).clm.) and ECA	USPAT; US-PGPUB	2003/03/22 11:51
-	55	((package near comprising).clm.) and 324/\$.ccls.	USPAT; US-PGPUB	2003/03/22 11:52
-	0	((package near comprising).clm.) and 324/\$.ccls.) and adhesive	USPAT; US-PGPUB	2003/03/22 11:52
-	194	((package near comprising).clm.) and conductive near2 adhesive	USPAT; US-PGPUB	2003/03/22 11:52
-	17	((package near comprising).clm.) and 324/\$.ccls.) and adhesive	USPAT; US-PGPUB	2003/03/22 11:53
-	194	((package near comprising).clm.) and conductive near2 adhesive	USPAT; US-PGPUB	2003/03/22 12:24
-	3	((package near comprising).clm.) and conductive near2 adhesive) and 324/\$.ccls.	USPAT; US-PGPUB	2003/03/22 11:57
-	104	((package near comprising).clm.) and conductive near2 adhesive) and 257/\$.ccls.	USPAT; US-PGPUB	2003/03/22 11:58
-	94	((((package near comprising).clm.) and conductive near2 adhesive) and 257/\$.ccls.) and bond\$	USPAT; US-PGPUB	2003/03/22 12:00
-	62	((((package near comprising).clm.) and conductive near2 adhesive) and 257/\$.ccls.) and wire adj bond\$	USPAT; US-PGPUB	2003/03/22 12:03
-	41	(((((package near comprising).clm.) and conductive near2 adhesive) and 257/\$.ccls.) and wire adj bond\$) and (gold indium)	USPAT; US-PGPUB	2003/03/22 12:22
-	2	(((((package near comprising).clm.) and conductive near2 adhesive) and 257/\$.ccls.) and wire adj bond\$) and indium	USPAT; US-PGPUB	2003/03/22 12:22
-	3	((package near comprising).clm.) and adhesive with indium	USPAT; US-PGPUB	2003/03/22 12:24
-	3	324/\$.ccls. and package and adhesive with indium	USPAT; US-PGPUB	2003/03/22 12:55
-	2	439/\$.ccls. and package and adhesive with indium	USPAT; US-PGPUB	2003/03/22 12:55
-	23	257/\$.ccls. and package and adhesive with indium	USPAT; US-PGPUB	2003/03/22 12:55
-	2	"6489178"	USPAT; US-PGPUB	2003/03/22 13:29
-	2	("5151276" "5897338").PN.	USPAT	2003/03/22 13:29
-	1059	438/118-119.cccls.	USPAT; US-PGPUB	2003/03/22 13:51
-	66	438/118-119.cccls. and indium	USPAT; US-PGPUB	2003/03/22 13:44
-	2	438/118-119.cccls. and adhesive with indium	USPAT; US-PGPUB	2003/03/22 13:44

-	1136	438/106.cccls.	USPAT; US-PGPUB	2003/03/22 13:53
-	2	438/106.cccls. and adhesive with indium	USPAT; US-PGPUB	2003/03/22 13:52
-	1394	438/14-15.cccls.	USPAT; US-PGPUB	2003/03/22 13:57
-	227	438/14-15.cccls. and adhesive	USPAT; US-PGPUB	2003/03/22 13:54
-	1	438/14-15.cccls. and adhesive with indium	USPAT; US-PGPUB	2003/03/22 13:54
-	530	438/15.cccls.	USPAT; US-PGPUB	2003/03/22 13:57
-	224	438/15.cccls. and therm\$	USPAT; US-PGPUB	2003/03/22 13:58
-	0	(438/15.cccls. and therm\$) and indium	USPAT; US-PGPUB	2003/03/22 13:58
-	16	(438/15.cccls. and therm\$) and indium	USPAT; US-PGPUB	2003/03/22 14:10
-	2	(("6251696") or ("5994716")).PN.	USPAT; US-PGPUB	2003/03/22 14:10
-	390	eutectic with indium	USPAT; US-PGPUB	2003/03/22 15:20
-	6	(eutectic with indium) and 324/\$.cccls.	USPAT; US-PGPUB	2003/03/22 15:24
-	574	aluminum with boron with beryllium with oxide	USPAT; US-PGPUB	2003/03/22 15:25
-	766	aluminum with boron with beryllium with oxide	USPAT; US-PGPUB	2003/03/22 15:25
-	192	aluminum with boron with beryllium with oxide with ceramic	USPAT; US-PGPUB	2003/03/22 15:26
-	0	(aluminum with boron with beryllium with oxide with ceramic) and 324/\$.cccls.	USPAT; US-PGPUB	2003/03/22 15:25
-	23	aluminum with boron with beryllium with oxide with ceramic with substrate	USPAT; US-PGPUB	2003/03/22 15:26
-	31	semiconductor near2 thermal near2 sensor	USPAT; US-PGPUB	2003/03/22 15:56
-	0	(semiconductor near2 thermal near2 sensor) and washer	USPAT; US-PGPUB	2003/03/22 15:57
-	11	(semiconductor near2 thermal near2 sensor) and mount	USPAT; US-PGPUB	2003/03/22 16:44
-	0	(semiconductor near2 thermal near2 sensor) and mount	EPO; JPO; DERWENT; IBM_TDB	2003/03/22 16:44
-	20	semiconductor near2 thermal near2 sensor	EPO; JPO; DERWENT; IBM_TDB	2003/03/22 16:44
-	2	(("6251696") or ("5126813")).PN.	USPAT; US-PGPUB	2003/03/22 17:27
-	1	((("6251696") or ("5126813")).PN.) and size	USPAT; US-PGPUB	2003/03/22 17:28
-	1	((("6251696") or ("5126813")).PN.) and mm	USPAT; US-PGPUB	2003/03/22 17:28